

Parameter	Value
$V_{CEO}$	50V
$I_C$	150mA

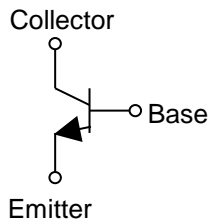
### ●Features

- 1) High DC current gain.  
 $h_{FE} = 2700$  (Max.)
- 2) High emitter-base voltage.  
 $V_{EBO}$  is Min. 12V
- 3) Low  $V_{CE(sat)}$   
 $V_{CE(sat)} = 0.3V$  (Max.)  
( $I_C/I_B = 50mA/5mA$ )
- 4) Lead Free/RoHS Compliant.

### ●Outline

<p>VMT3</p> <p>2SD2707 (SC-105AA)</p>	<p>EMT3</p> <p>2SD2654 SOT-416 (SC-75A)</p>
<p>UMT3</p> <p>2SD2351 SOT-323 (SC-70)</p>	<p>SMT3</p> <p>2SD2226K SOT-346 (SC-59)</p>

### ●Inner circuit



### ●Applications

Muting circuit

### ●Packaging specifications

Part No.	$h_{FE}$	Package	Package size (mm)	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit (pcs)	Marking
2SD2707	V	VMT3	1212	T2L	180	8	8,000	BJx <sup>*1</sup>
2SD2654	VW	EMT3	1616	TL	180	8	3,000	BJx <sup>*1</sup>
2SD2351	VW	UMT3	2021	T106	180	8	3,000	BJx <sup>*1</sup>
2SD2226K	VW	SMT3	2928	T146	180	8	3,000	BJx <sup>*1</sup>

\*1 x :  $h_{FE}$  rank

● **Absolute maximum ratings** (Ta = 25°C)

Parameter	Symbol	Values	Unit
Collector-base voltage	$V_{CBO}$	60	V
Collector-emitter voltage	$V_{CEO}$	50	V
Emitter-base voltage	$V_{EBO}$	12	V
Collector current	$I_C$	150	mA
	$I_{CP}^{*1}$	200	mA
Power dissipation	2SD2226K,2SD2351	200	mW
	2SD2351,2SD2707	150	mW
Junction temperature	$T_j$	150	°C
Range of storage temperature	$T_{stg}$	-55 to +150	°C

● **Electrical characteristics** (Ta = 25°C)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Collector-emitter breakdown voltage	$BV_{CEO}$	$I_C = 1\text{mA}$	50	-	-	V
Collector-base breakdown voltage	$BV_{CBO}$	$I_C = 10\mu\text{A}$	60	-	-	V
Emitter-base breakdown voltage	$BV_{EBO}$	$I_E = 10\mu\text{A}$	12	-	-	V
Collector cut-off current	$I_{CBO}$	$V_{CB} = 50\text{V}$	-	-	0.3	$\mu\text{A}$
Emitter cut-off current	$I_{EBO}$	$V_{EB} = 12\text{V}$	-	-	0.3	$\mu\text{A}$
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 50\text{mA}, I_B = 5\text{mA}$	-	-	0.3	V
DC current gain	$h_{FE}$	$V_{CE} = 5\text{V}, I_C = 1\text{mA}$	820	-	2700	-
Transition frequency	$f_T$	$V_{CE} = 5\text{V}, I_E = -10\text{mA}$ $f = 100\text{MHz}$	-	250	-	MHz
Output capacitance	$C_{ob}$	$V_{CB} = 5\text{V}, I_E = 0\text{mA}$ $f = 1\text{MHz}$	-	3.5	-	pF

\*1  $P_W = 10\text{ms}$  Single pulse.

\*2 Each terminal mounted on a reference footprint

●  **$h_{FE}$  rank categories**

Rank	V	W
$h_{FE}$	820 to 1800	1200 to 2700

●Electrical characteristic curves(Ta = 25°C)

Fig.1 Ground Emitter Propagation Characteristics

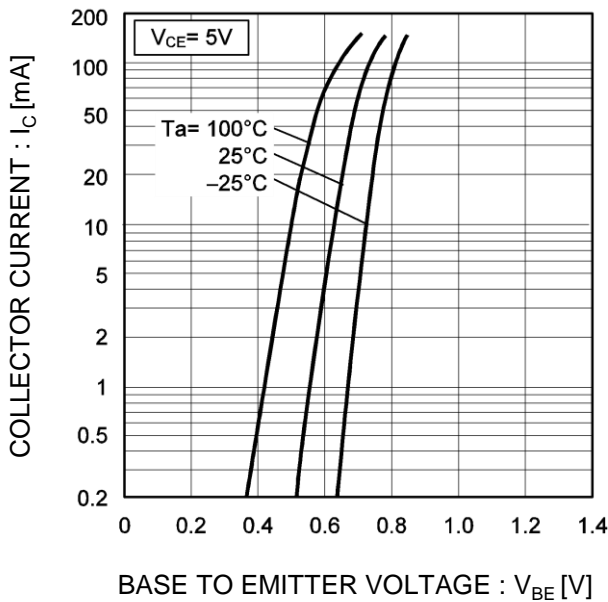


Fig.2 Typical Output Characteristics

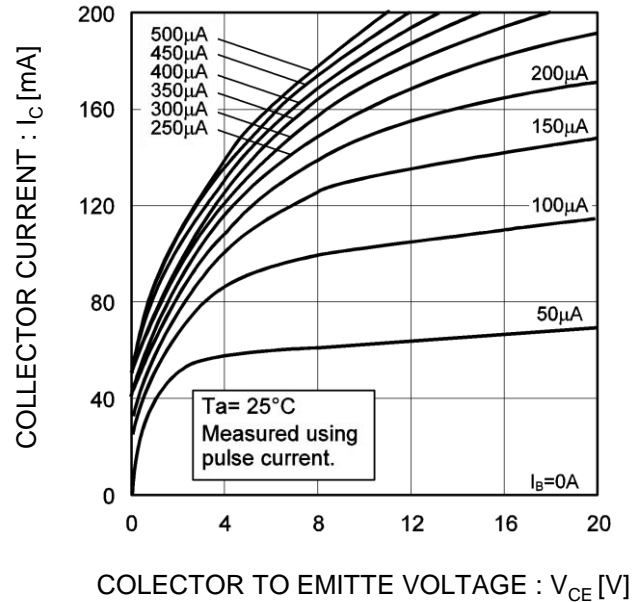


Fig.3 DC Current Gain vs. Collector Current(I)

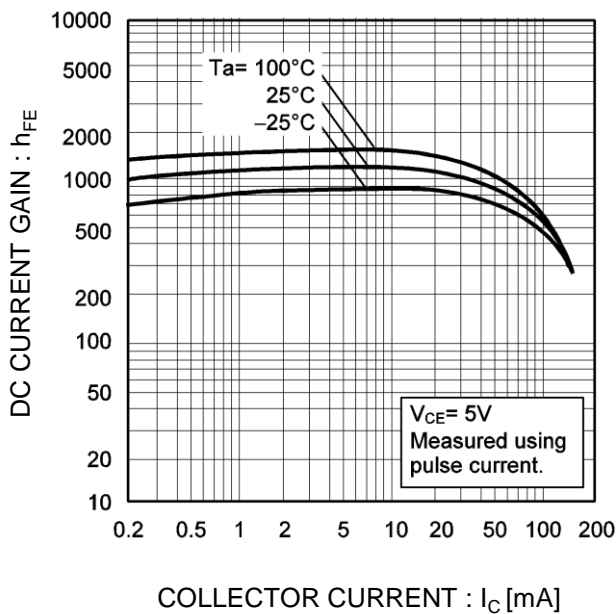
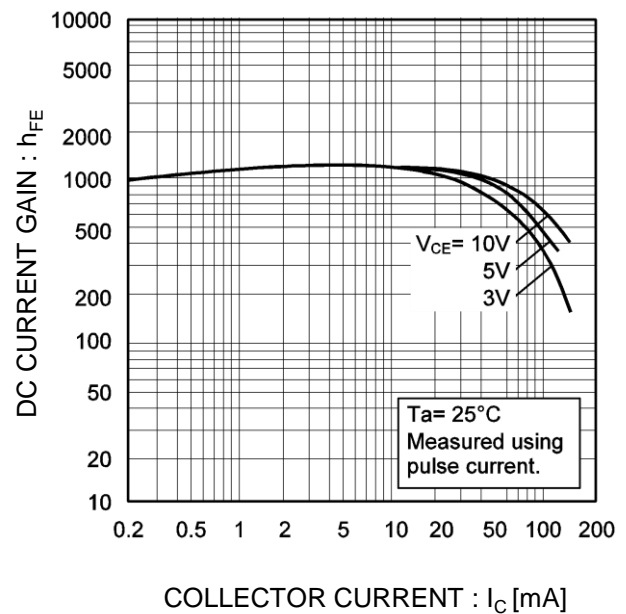


Fig.4 DC Current Gain vs. Collector Current(II)



●Electrical characteristic curves(Ta = 25°C)

Fig.5 Collector-Emitter Saturation Voltage vs. Collector Current (I)

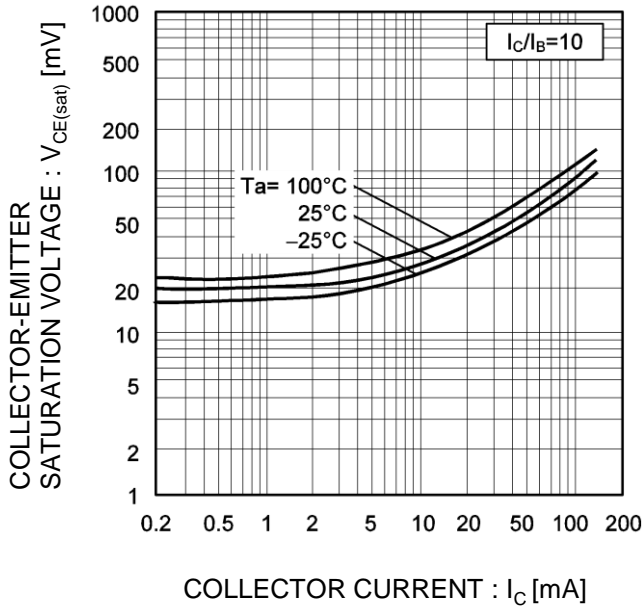


Fig.6 Collector-Emitter Saturation Voltage vs. Collector Current (II)

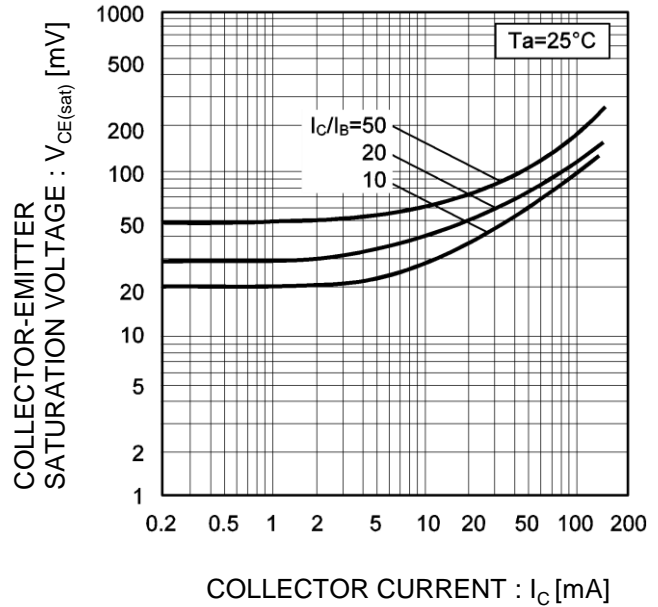


Fig.7 Base-Emitter Saturation Voltage vs. Collector Current

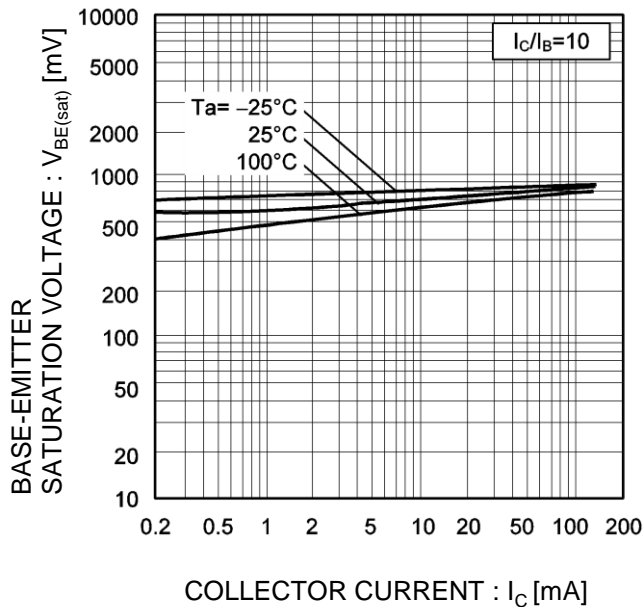
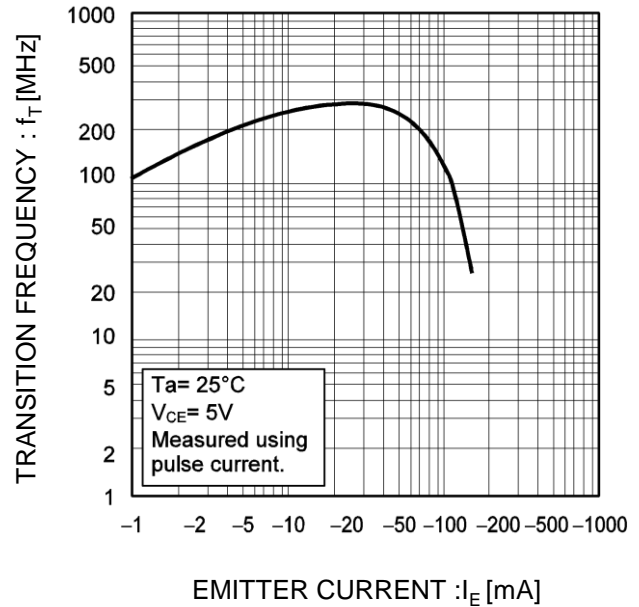


Fig.8 Gain Bandwidth Product vs. Emitter Current



●Electrical characteristic curves(Ta = 25°C)

Fig.9 Emitter input capacitance vs. Emitter-Base Voltage  
Collector output capacitance vs. Collector-Base Voltage

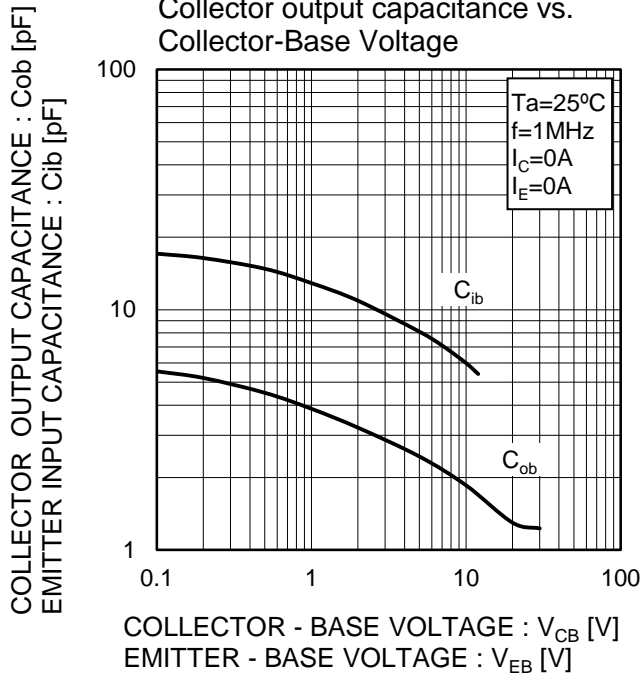


Fig.10 ON-state resistance vs. base current characteristics

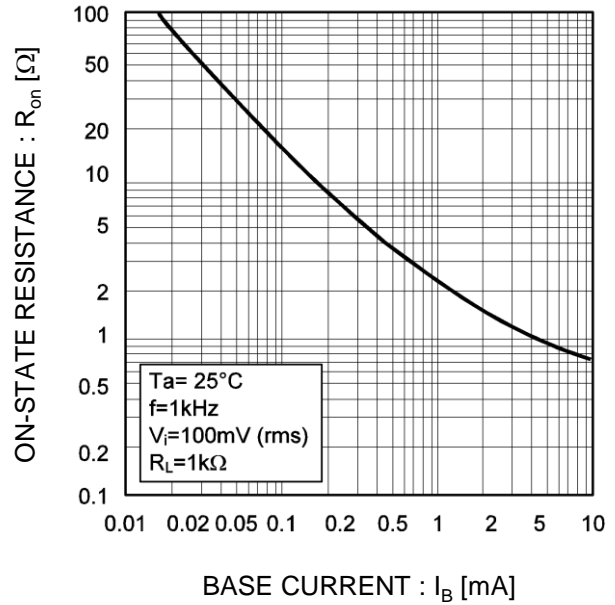


Fig.11 Safe Operating Area

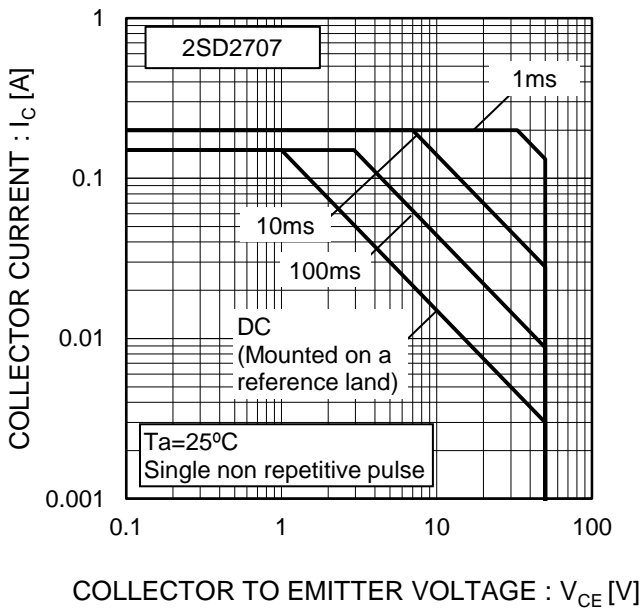
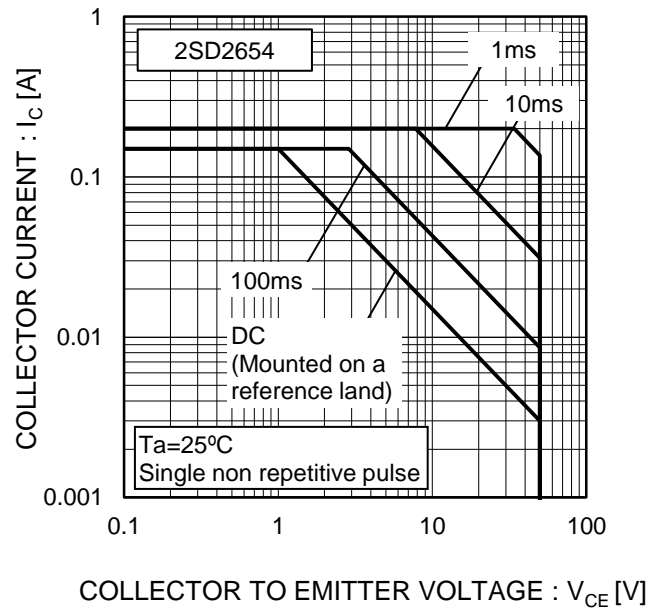


Fig.12 Safe Operating Area



●Electrical characteristic curves(Ta = 25°C)

Fig.13 Safe Operating Area

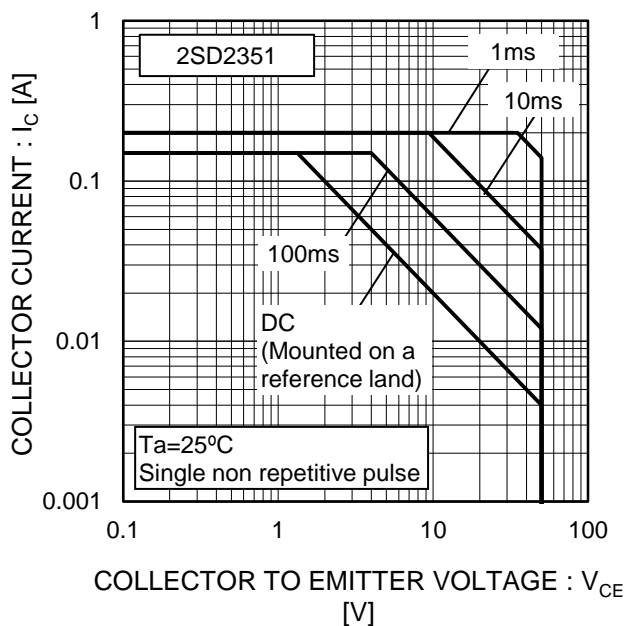
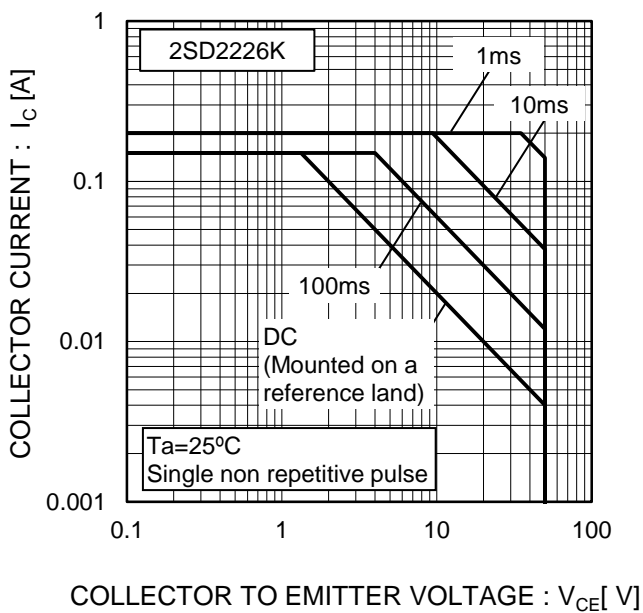
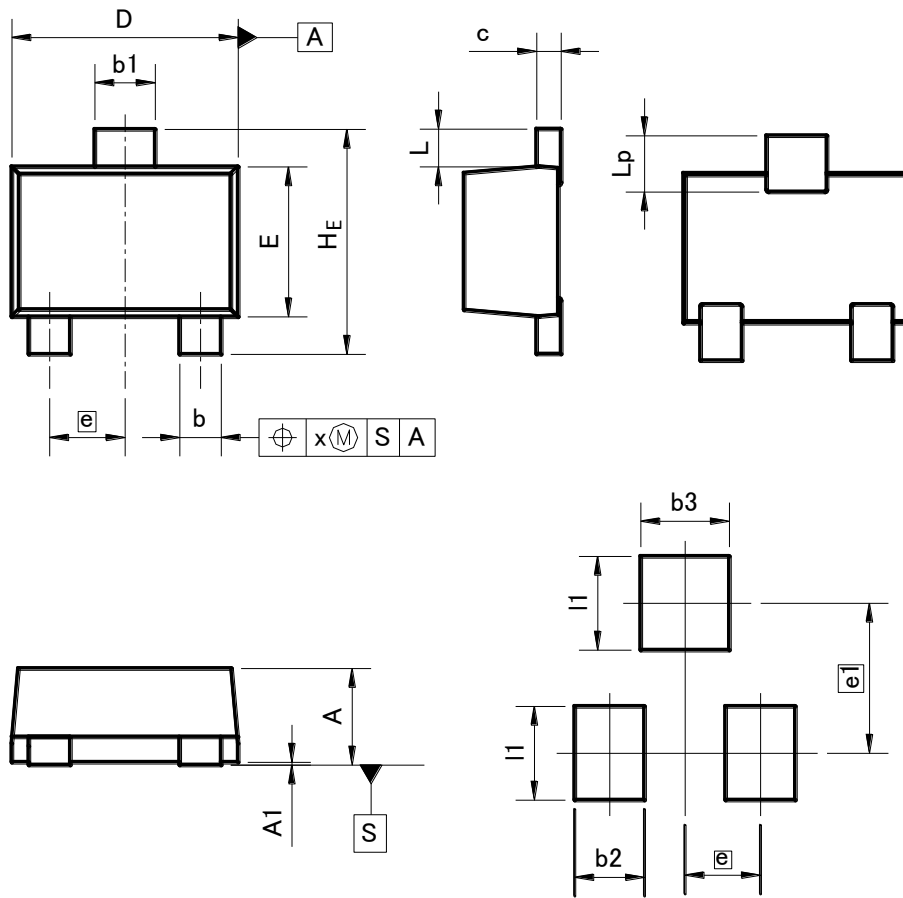


Fig.14 Safe Operating Area



●Dimensions (Unit : mm)

VMT3



Pattern of terminal position areas  
[Not a recommended pattern of soldering pads]

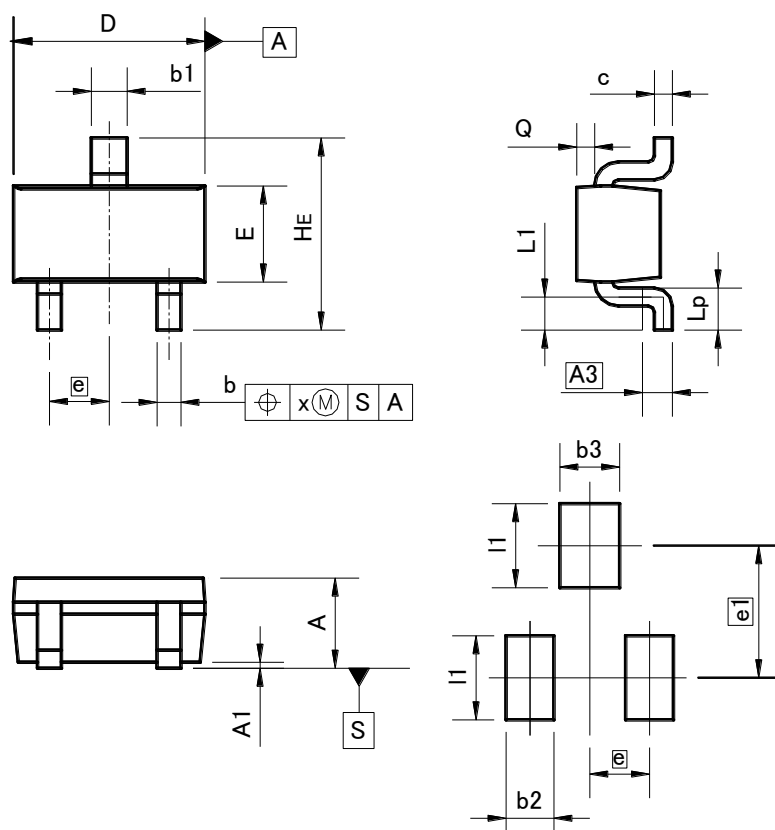
DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
b1	0.27	0.37	0.011	0.015
c	0.08	0.18	0.003	0.007
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
e	0.40		0.02	
HE	1.10	1.30	0.043	0.051
L	0.10	0.30	0.004	0.012
Lp	0.20	0.40	0.008	0.016
x	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.37	-	0.015
b3	-	0.47	-	0.019
e1	0.80		0.031	
l1	-	0.50	-	0.020

Dimension in mm / inches

●Dimensions (Unit : mm)

EMT3



DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.60	0.80	0.024	0.031
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.15	0.30	0.006	0.012
b1	0.25	0.40	0.010	0.016
c	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
e	0.50		0.020	
HE	1.40	1.80	0.055	0.071
L1	0.10	-	0.004	-
Lp	0.15	-	0.006	-
Q	0.05	0.25	0.002	0.010
x	-	0.10	-	0.004

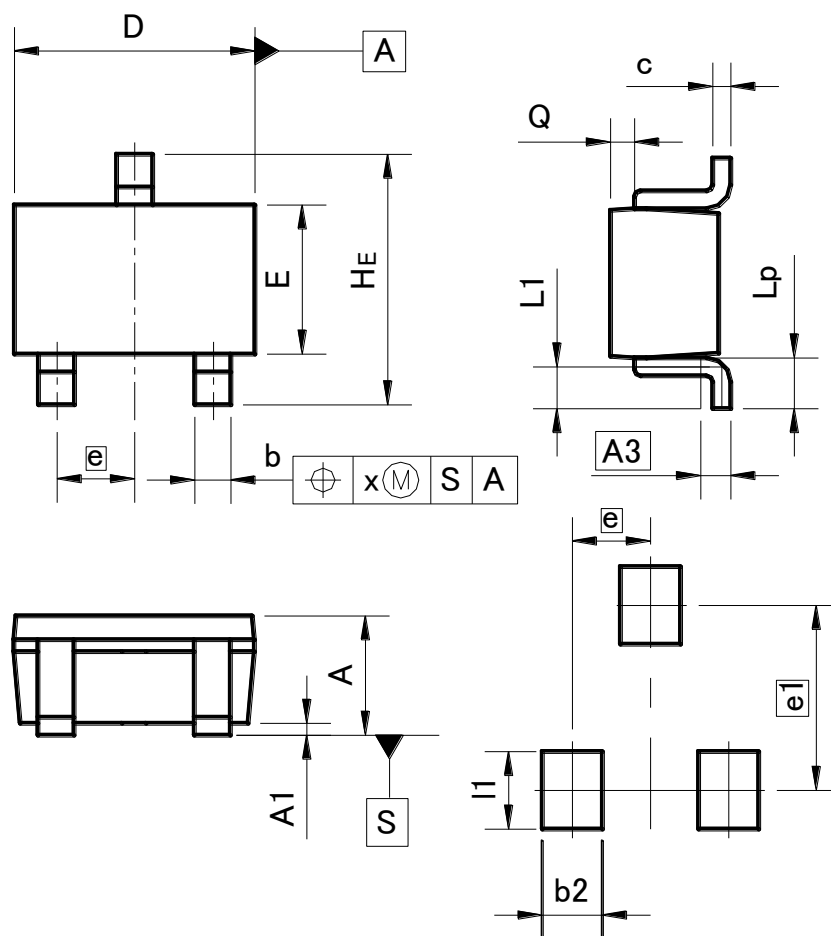
DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.40	-	0.016
b3	-	0.50	-	0.020
e1	1.10		0.043	
l1	-	0.70	-	0.028

Dimension in mm / inches



●Dimensions (Unit : mm)

UMT3



Pattern of terminal position areas  
[Not a recommended pattern of soldering pads]

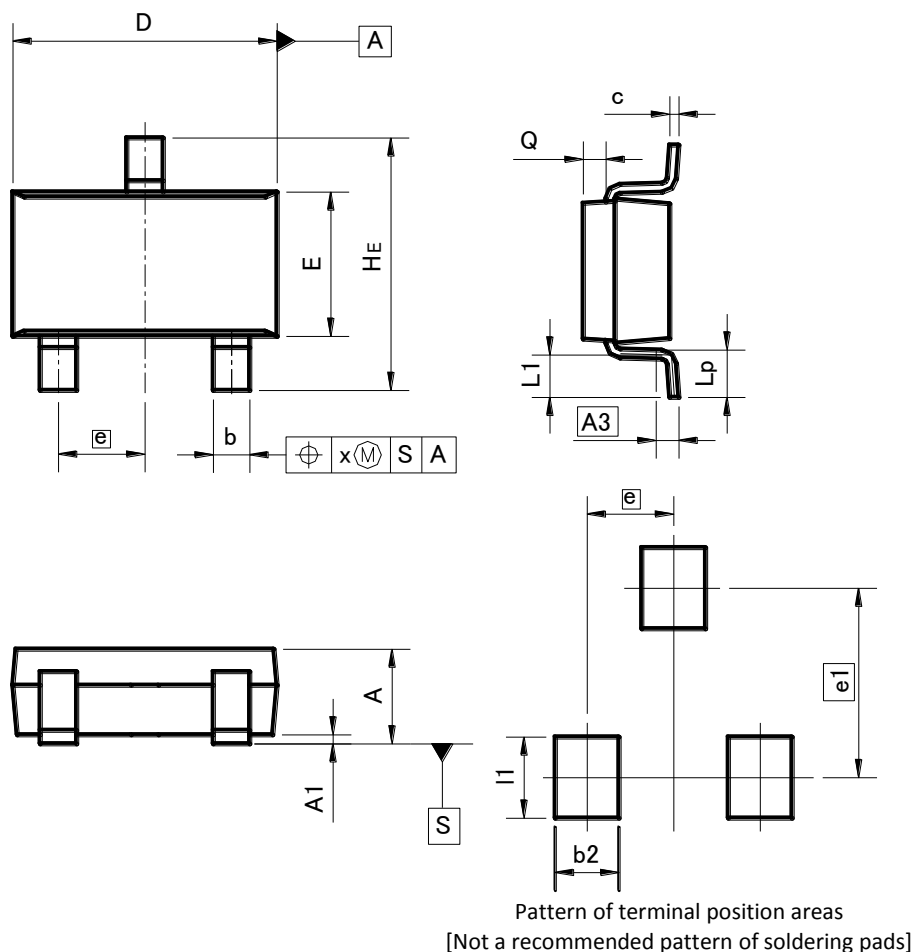
DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.15	0.30	0.006	0.012
c	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
e	0.65		0.026	
HE	2.00	2.20	0.079	0.087
L1	0.20	0.50	0.008	0.020
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
x	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.50	-	0.020
e1	1.55		0.061	
l1	-	0.65	-	0.026

Dimension in mm / inches

●Dimensions (Unit : mm)

SMT3



Pattern of terminal position areas  
[Not a recommended pattern of soldering pads]

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.35	0.50	0.014	0.020
c	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
e	0.95		0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
x	-	0.10	-	0.004
y	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.60	-	0.024
e1	2.10		0.083	
l1	-	0.90	-	0.035

Dimension in mm / inches

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